

LSI DOCKET NO. 01-379

ABSTRACT OF THE DISCLOSURE

AUTOMARKING, PATTERNLESS, WAFER SCALE TESTING

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The present invention addresses the problem of testing newly-manufactured integrated circuits at the wafer stage. Built-in self-test circuitry is used to test each of the die on a wafer in parallel. Then, when a defect is detected, the die marks itself (e.g., by physically destroying a portion of itself through burnout). The present invention eliminates the inefficiencies of serial testing of die and of mechanical latency as each die is positioned for testing.

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